

FIG. 1A

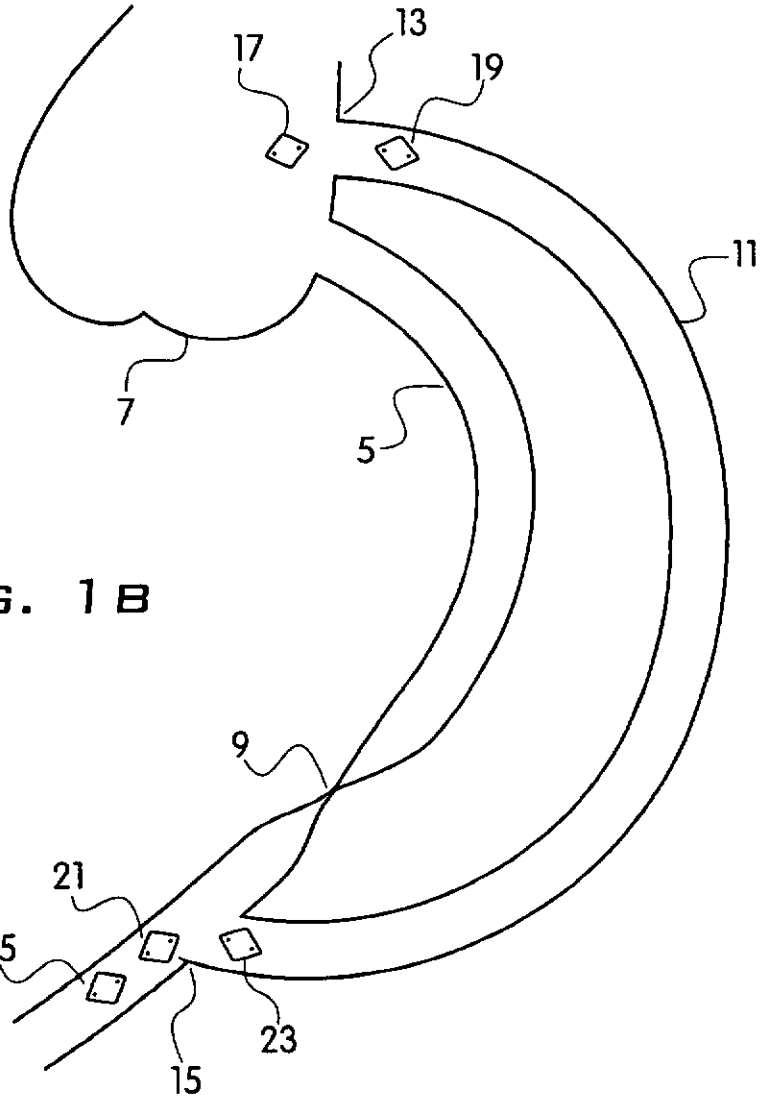


FIG. 1B

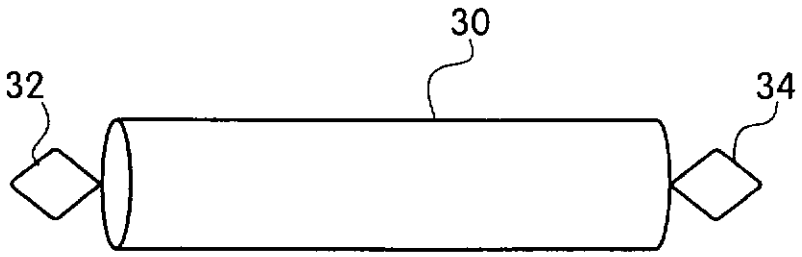


FIG. 2A

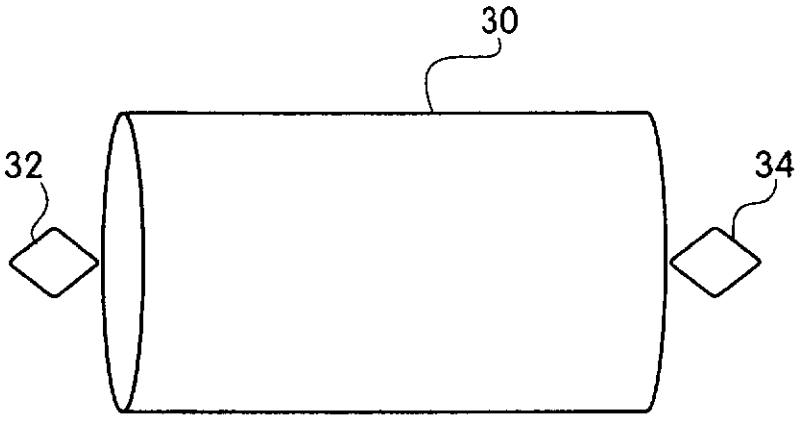


FIG. 2B

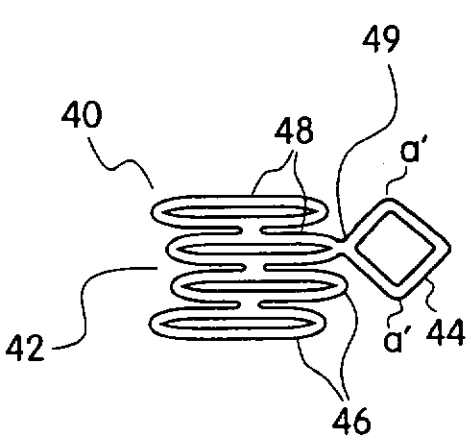


FIG. 3A

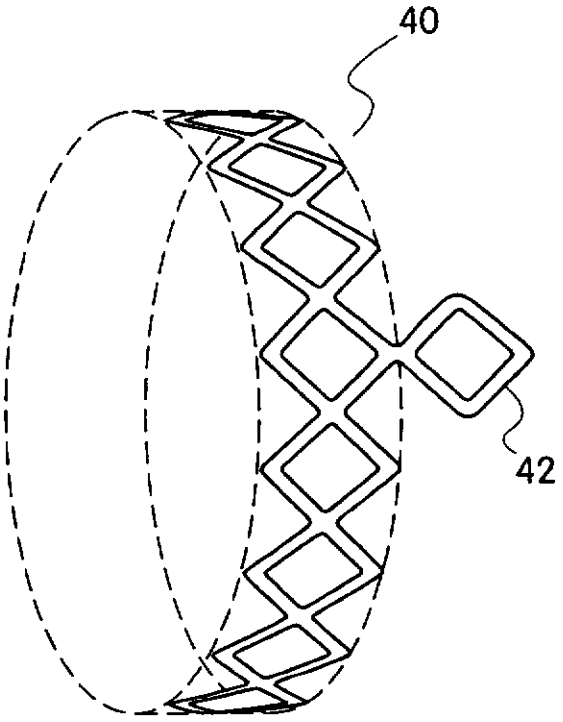


FIG. 3B

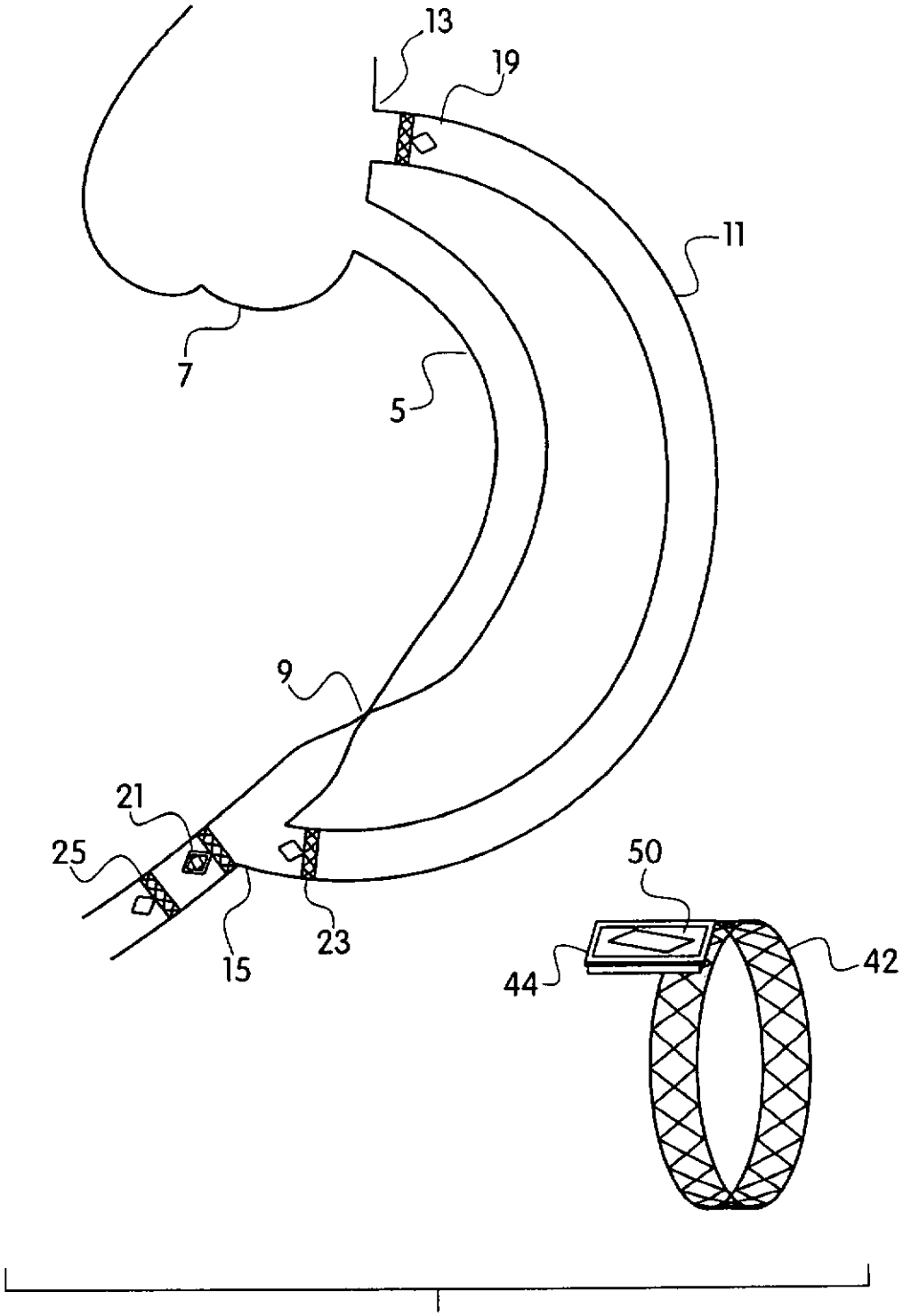


FIG. 4

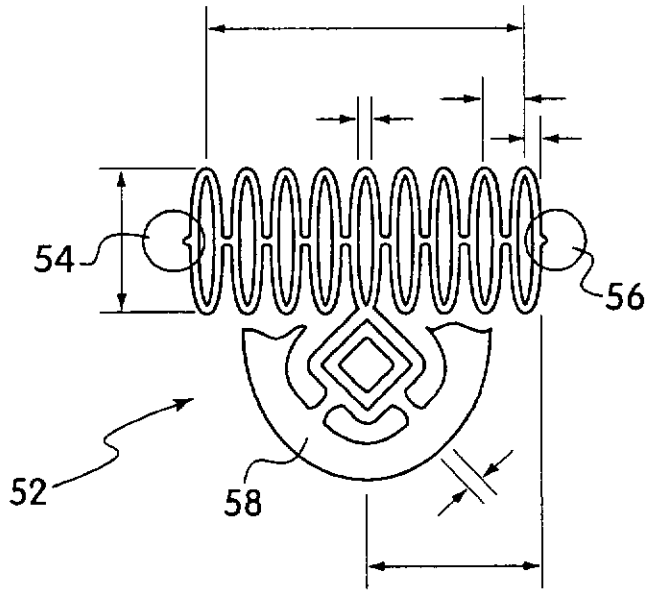


FIG. 5

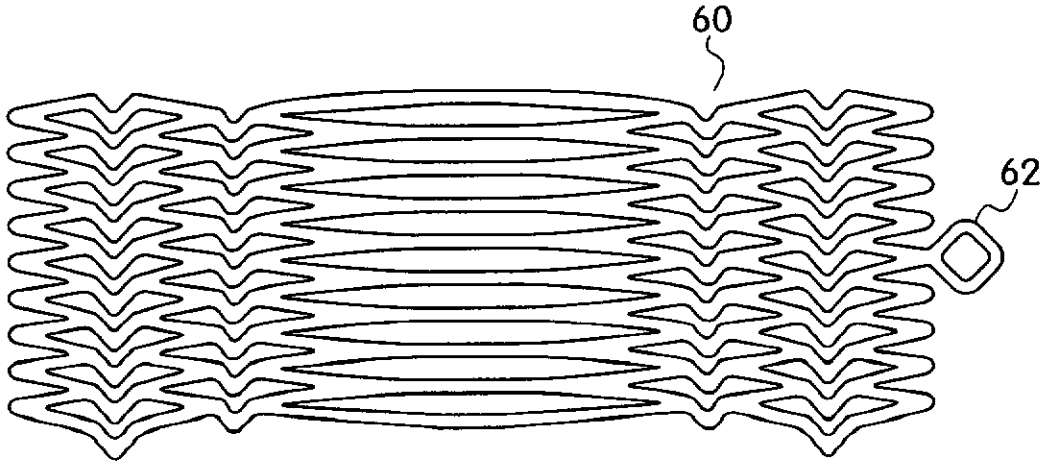


FIG. 6

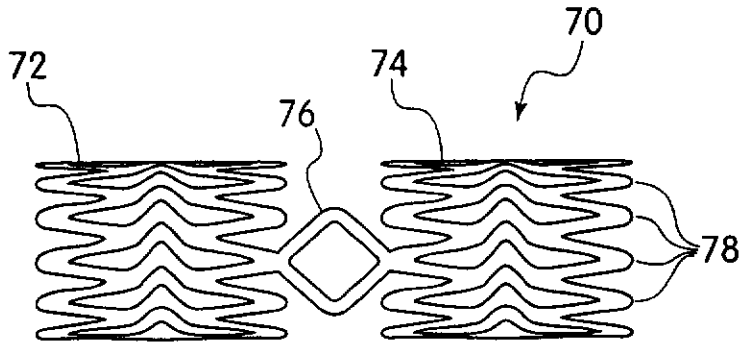


FIG. 7

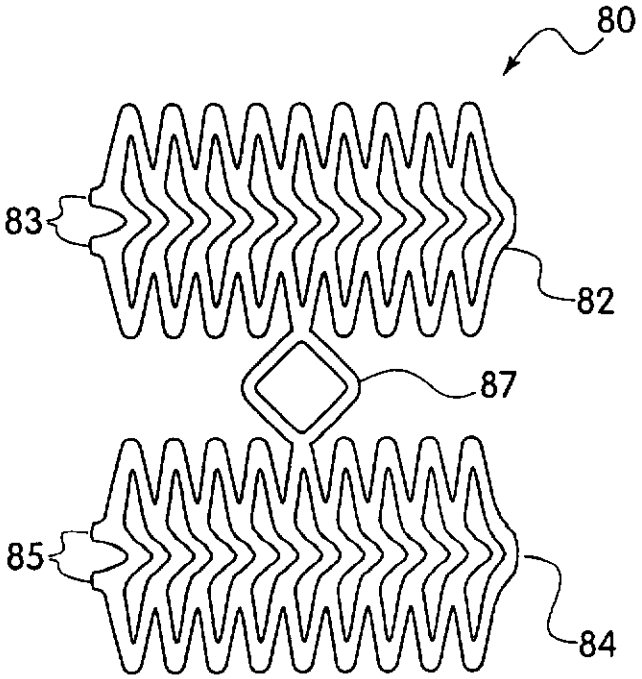


FIG. 8

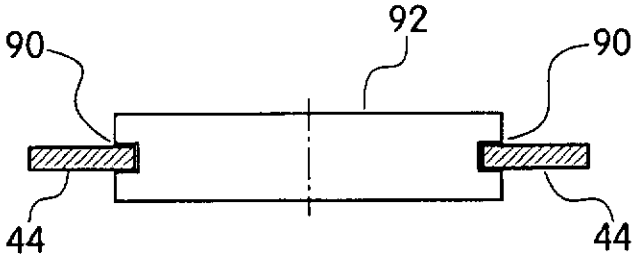


FIG. 9A

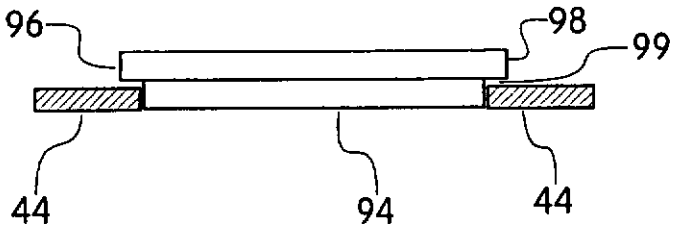


FIG. 9B

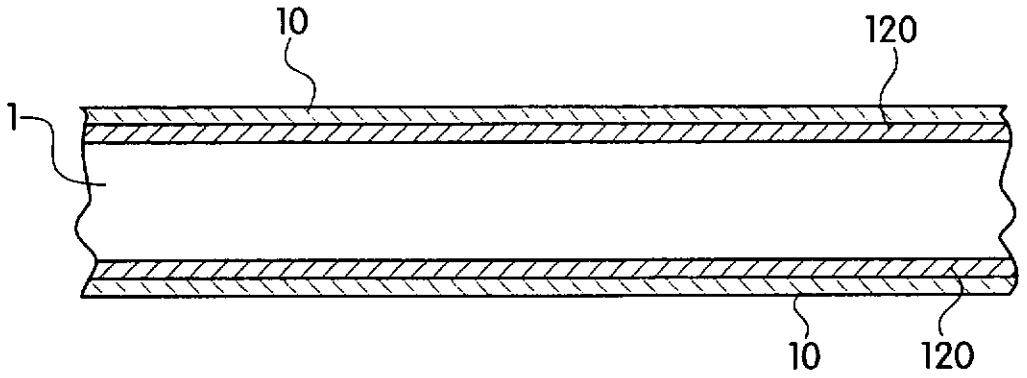


FIG. 10A

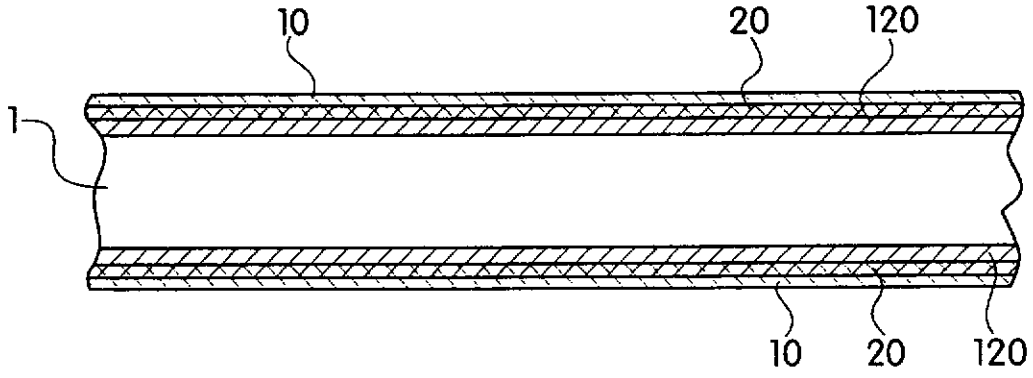


FIG. 10B

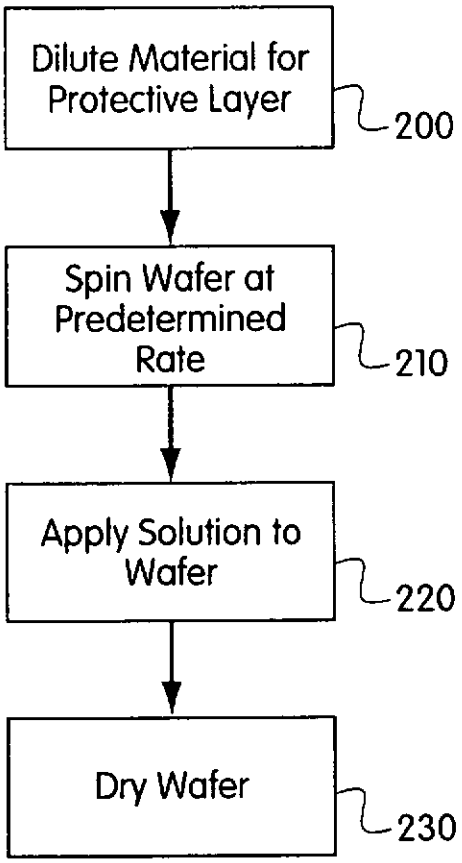

Dilute Material for Protective Layer
200
Spin Wafer at Predetermined Rate
210
Apply Solution to Wafer
220
Dry Wafer
230

FIG. 10C

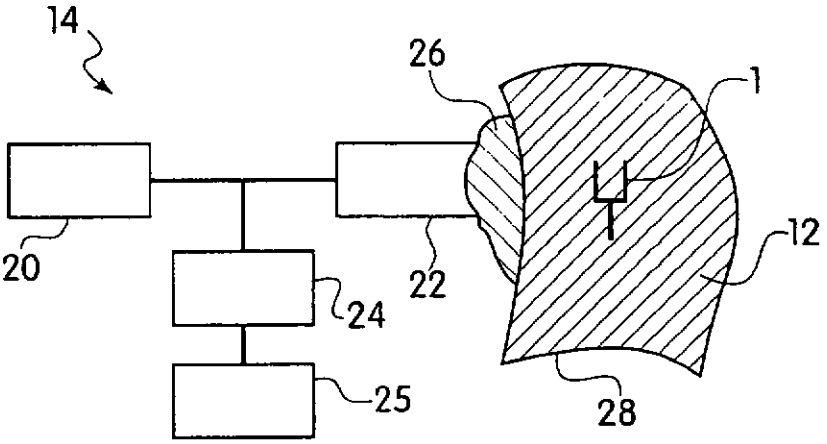


FIG. 11

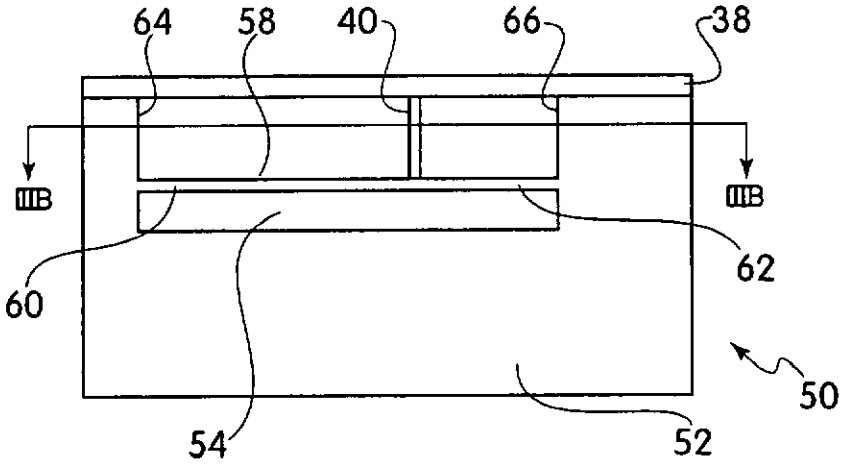


FIG. 13A

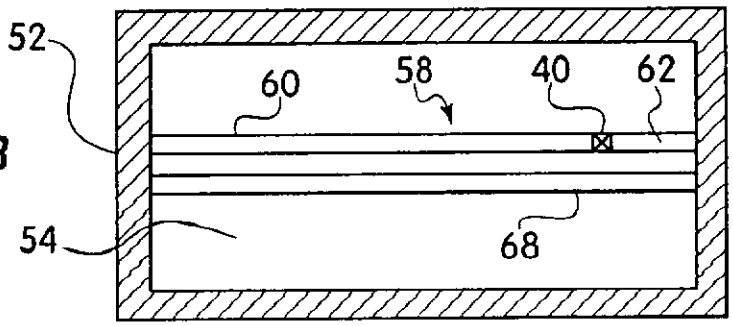


FIG. 13B

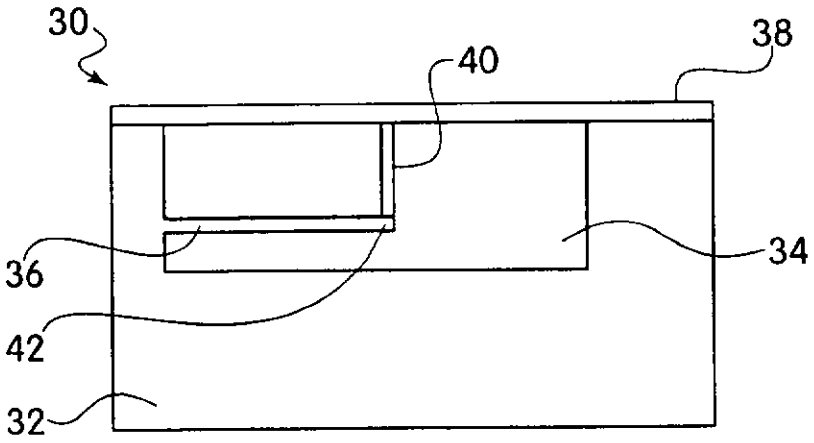


FIG. 12A

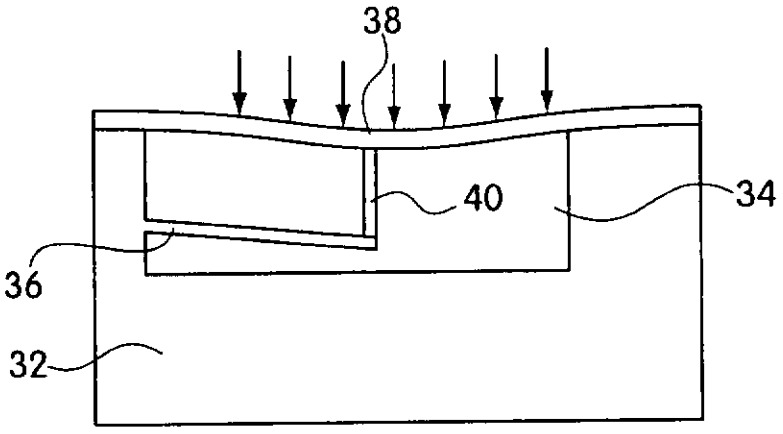


FIG. 12B

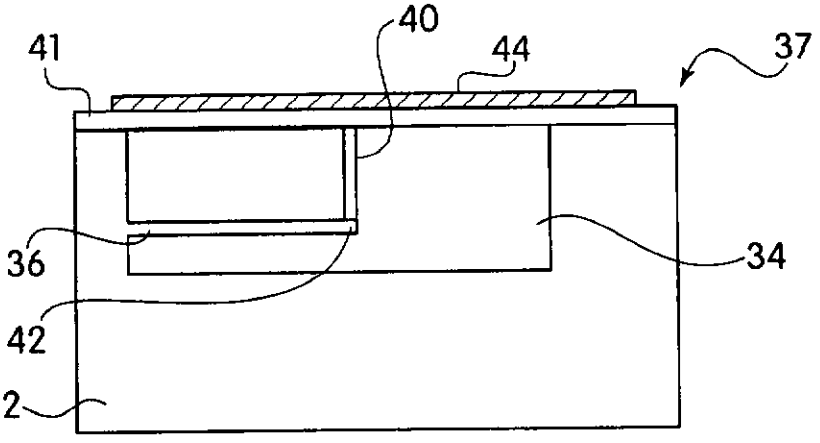


FIG. 12C

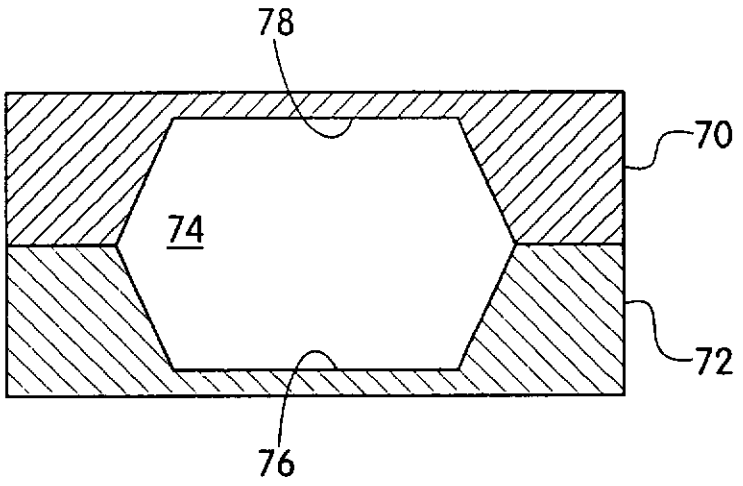


FIG. 14A

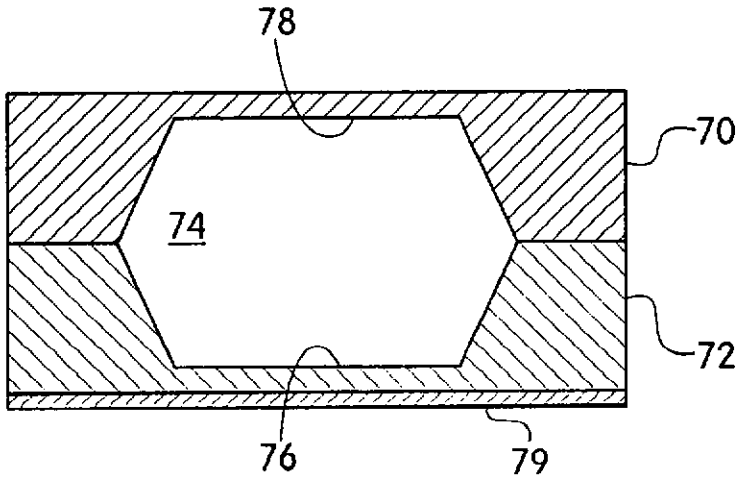


FIG. 14B

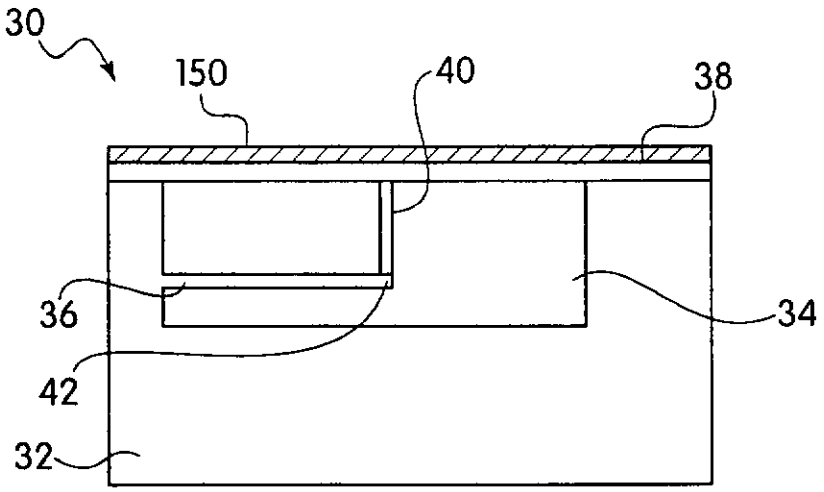


FIG. 15

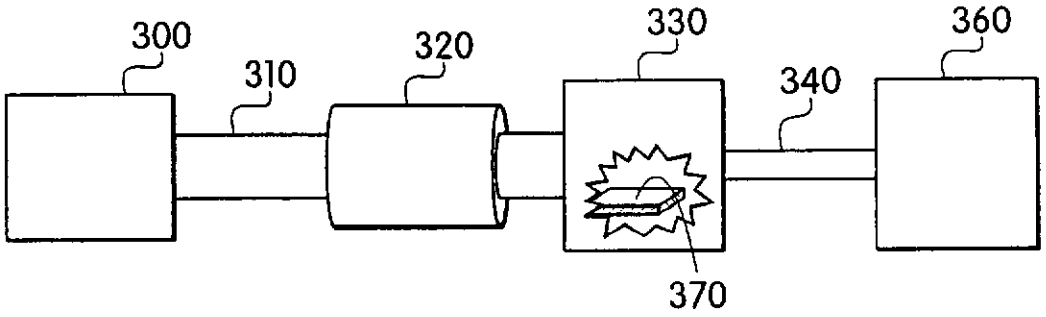


FIG. 16